



# SOT2114-1(D)

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

18 May 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN68
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	08-09-2016
<b>Manufacturer package code</b>	MV-A301037-00

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	68	-	



HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

2 Package outline

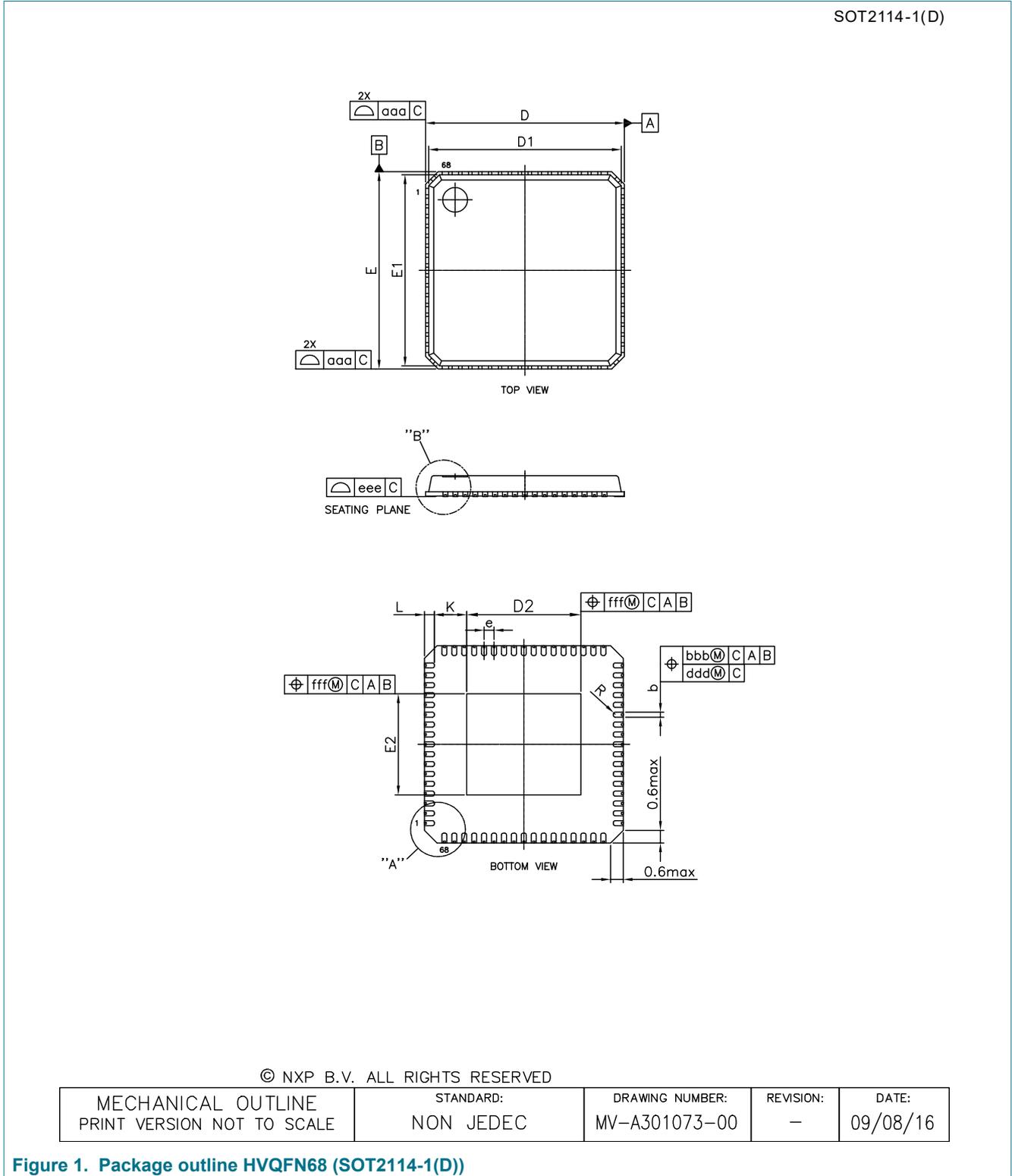


Figure 1. Package outline HVQFN68 (SOT2114-1(D))

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

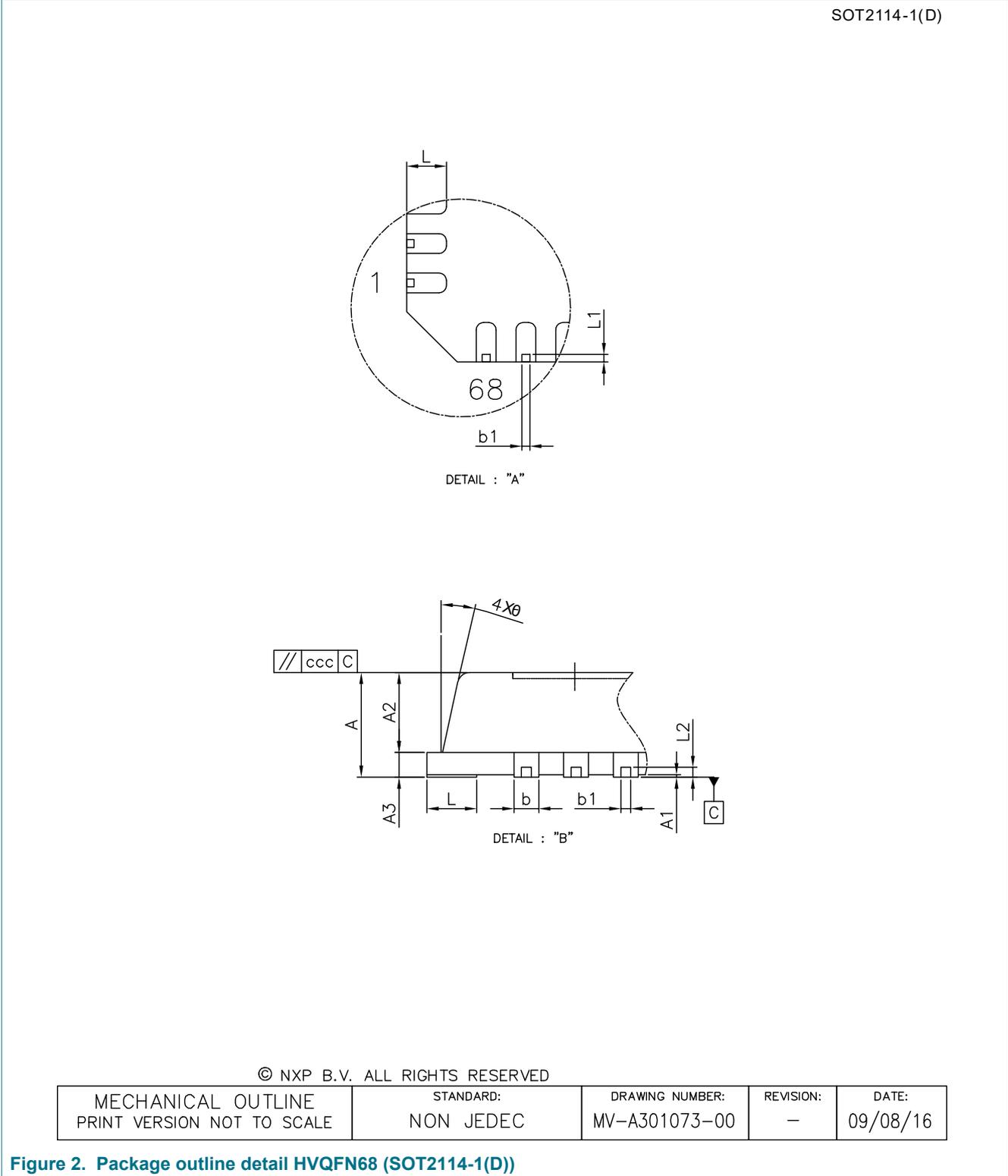


Figure 2. Package outline detail HVQFN68 (SOT2114-1(D))

HVQFN68, thermal enhanced very thin quad flat package, no leads, 68 terminals, 0.4 mm pitch, 8 mm x 8 mm x 0.85 mm body

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Symbol	Dimension in mm		
	MIN	NOM	MAX
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A2	0.60	0.65	0.70
A3	0.20 REF		
b	0.15	0.20	0.25
b1	0.03	0.08	0.13
D/E	7.90	8.00	8.10
D1/E1	7.75 BSC		
D2	4.50	4.60	4.70
E2	4.00	4.10	4.20
e	0.40 BSC		
L	0.30	0.40	0.50
L1	0.025	0.075	0.125
L2	0.025	0.080	0.135
θ	0°	---	14°
R	0.075	---	0.125
K	0.20	---	---
aaa	0.10		
bbb	0.07		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

NOTE:

1. CONTROLLING DIMENSION : MILLIMETER
2. REFERENCE DOCUMENT : JEDEC MO-220.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV-A301073-00	REVISION: -	DATE: 09/08/16
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Figure 3. Package outline note HVQFN68 (SOT2114-1(D))

### 3 Legal information

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Contents

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1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....5